

Title (en)

METHOD AND APPARATUS FOR ELECTROLESS PLATING

Publication

EP 0141507 A3 19850710 (EN)

Application

EP 84306103 A 19840906

Priority

GB 8324060 A 19830908

Abstract (en)

[origin: EP0141507A2] An electroless plating process in which an article is plated while immersed in a plating solution containing a plating metal such as nickel and a reducing agent such as hypophosphate is modified by applying an electrical potential difference between the article, as cathode, and an anode in electrical contact with the plating solution. The current density is generally far below that required to cause electroplating and preferably is 0.01 to 0.05 A/dm² on the cathodic article surface.

IPC 1-7

C23C 18/16; **C23C 18/34**

IPC 8 full level

C23C 18/36 (2006.01); **C23C 18/52** (2006.01)

CPC (source: EP)

C23C 18/36 (2013.01); **C23C 18/52** (2013.01)

Citation (search report)

- [X] US 3303111 A 19670207 - PEACH ARTHUR L
- [X] US 3485725 A 19691223 - KORETZKY HERMAN
- [X] DE 1278188 B 19680919 - SIEMAG SIEGENER MASCH BAU
- [X] US 3264199 A 19660802 - FASSELL JR WAYNE MARTIN, et al
- [A] US 3864148 A 19750204 - MAEAWA MINORU, et al
- [A] US 2837445 A 19580603 - PAUL TALMEY, et al

Cited by

EP0237663A1

Designated contracting state (EPC)

BE DE FR GB IT NL

DOCDB simple family (publication)

EP 0141507 A2 19850515; **EP 0141507 A3 19850710**; GB 8324060 D0 19831012

DOCDB simple family (application)

EP 84306103 A 19840906; GB 8324060 A 19830908